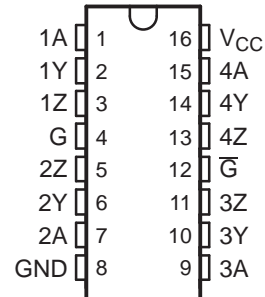


LOW-VOLTAGE HIGH-SPEED QUADRUPLE DIFFERENTIAL LINE DRIVER WITH ± 15 -kV IEC ESD PROTECTION

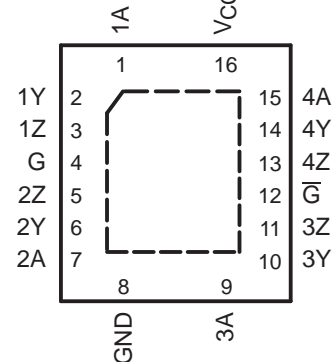
FEATURES

- Meets or Exceeds Standards TIA/EIA-422-B and ITU Recommendation V.11
- Operates From a Single 3.3-V Power Supply
- ESD Protection for RS422 Bus Pins
 - ± 15 -kV Human-Body Model (HBM)
 - ± 8 -kV IEC61000-4-2, Contact Discharge
 - ± 15 -kV IEC61000-4-2, Air-Gap Discharge
- Switching Rates up to 32 MHz
- Propagation Delay Time . . . 8 ns Typ
- Pulse Skew Time . . . 500 ps Typ
- High Output-Drive Current . . . ± 30 mA
- Controlled Rise and Fall Times . . . 5 ns Typ
- Differential Output Voltage With 100- Ω Load . . . 2.6 V Typ
- Accepts 5-V Logic Inputs With 3.3-V Supply
- I_{off} Supports Partial-Power-Down Mode Operation
- Driver Output Short-Protection Circuit
- Glitch-Free Power-Up/Power-Down Protection
- Package Options: SOP, SOIC, TSSOP, QFN

D, NS, OR PW PACKAGE
(TOP VIEW)



RGY PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The AM26LV31E is a quadruple differential line driver with 3-state outputs. This driver has ± 15 -kV ESD (HBM and IEC61000-4-2, Air-Gap Discharge) and ± 8 -kV ESD (IEC61000-4-2, Contact Discharge) protection. This device is designed to meet TIA/EIA-422-B and ITU Recommendation V.11 drivers with reduced supply voltage.

The device is optimized for balanced-bus transmission at switching rates up to 32 MHz. The outputs have high current capability for driving balanced lines, such as twisted-pair transmission lines, and provide a high impedance in the power-off condition.

The AM26LV31E is characterized for operation from -40°C to 85°C .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SOIC – D	Tape and reel	AM26LV31EIDR	AM26LV31EI
	SOP – NS	Tape and reel	AM26LV31EINSR	26LV31EI
	TSSOP – PW	Tape and reel	AM26LV31EIPWR	SB31
	QFN – RGY	Tape and reel	AM26LV31EIRGYR	SB31

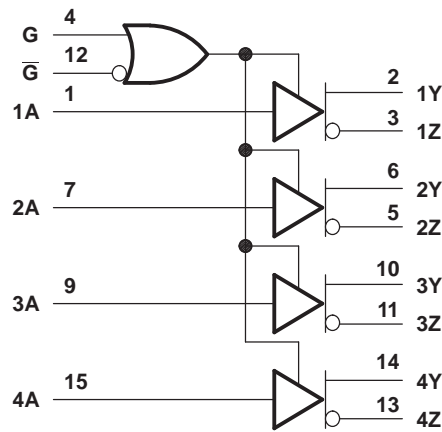
- (1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

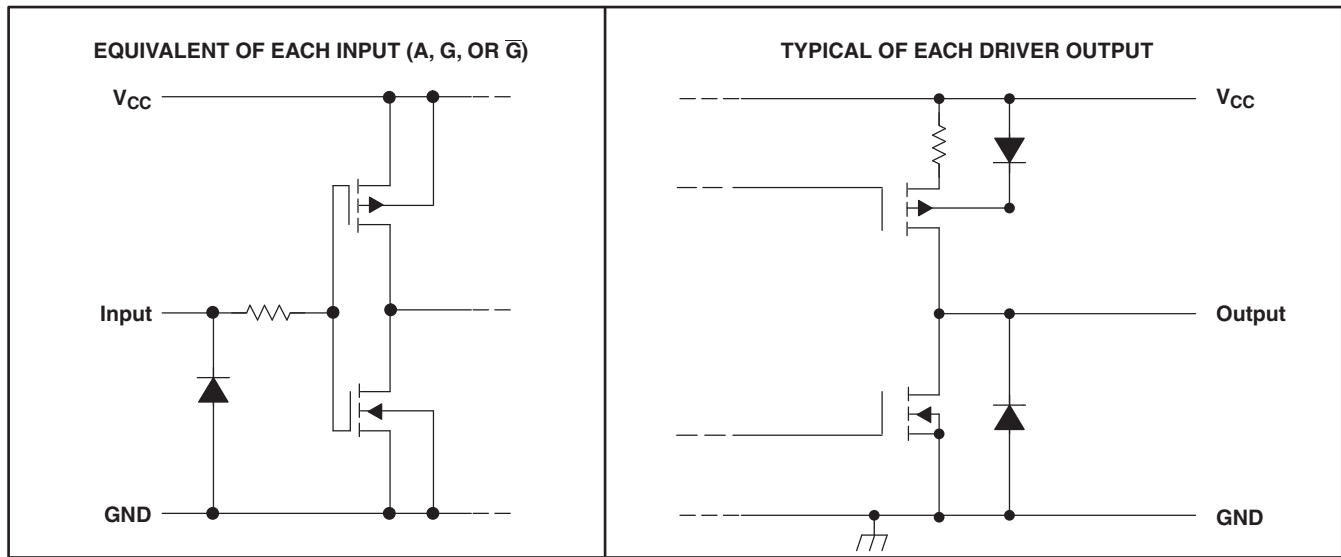
FUNCTION TABLE⁽¹⁾

INPUT A	ENABLES		OUTPUTS	
	G	\bar{G}	Y	Z
H	H	X	H	L
L	H	X	L	H
H	X	L	H	L
L	X	L	L	H
X	L	H	Z	Z

- (1) H = high level, L = low level, X = irrelevant, Z = high impedance (off)

LOGIC DIAGRAM



SCHEMATIC

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range ⁽²⁾	-0.5	6	V
V_I	Input voltage range	-0.5	6	V
V_O	Output voltage range	-0.5	6	V
I_{IK}	Input clamp current	$V_I < 0$		-20 mA
I_{OK}	Output clamp current	$V_O < 0$		-20 mA
I_O	Continuous output current			±150 mA
	Continuous current through V_{CC} or GND			±200 mA
T_J	Operating virtual junction temperature			150 °C
θ_{JA}	Package thermal impedance ⁽³⁾⁽⁴⁾	D package		73
		NS package		64
		PW package		108
		RGY package		39
T_A	Operating free-air temperature range	-40	85	°C
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values except differential input voltage are with respect to the network GND.
- (3) Maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} - T_A)/\theta_{JA}$. Selecting the maximum of 150°C can affect reliability.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

		MIN	TYP	MAX	UNIT
V_{CC}	Supply voltage	3	3.3	3.6	V
V_I	Input voltage	0		5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{OH}	High-level output current			–30	mA
I_{OL}	Low-level output current			30	mA
T_A	Operating free-air temperature	–40		85	°C

ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT	
V_{OH}	High-level output voltage	$V_{IH} = 2\text{ V}$, $V_{IL} = 0.8\text{ V}$, $I_{OH} = -20\text{ mA}$	2.4	3	V	
V_{OL}	Low-level output voltage	$V_{IH} = 2\text{ V}$, $V_{IL} = 0.8\text{ V}$, $I_{OL} = 20\text{ mA}$		0.2	0.4	V
$ V_{OD1} $	Differential output voltage	$I_O = 0\text{ mA}$	2		4	V
$ V_{OD2} $	Differential output voltage	$R_L = 100\ \Omega$ (see Figure 1) ⁽²⁾	2	2.6		V
$\Delta V_{OD} $	Change in magnitude of differential output voltage	$R_L = 100\ \Omega$ (see Figure 1) ⁽²⁾			± 0.4	V
V_{OC}	Common-mode output voltage	$R_L = 100\ \Omega$ (see Figure 1) ⁽²⁾		1.5	2	V
$\Delta V_{OC} $	Change in magnitude of common-mode output voltage	$R_L = 100\ \Omega$ (see Figure 1) ⁽²⁾			± 0.4	V
$I_{O(OFF)}$	Output current with power off	$V_{CC} = 0$, $V_O = -0.25\text{ V}$ or 5.5 V			± 100	μA
I_{OZ}	High-impedance state output current	$V_O = -0.25\text{ V}$ or 5.5 V , $G = 0.8\text{ V}$ or $\overline{G} = 2\text{ V}$			± 100	μA
I_I	Input current	$V_{CC} = 0$ or 3.6 V , $V_I = 0$ or 5.5 V			± 10	μA
I_{OS}	Short-circuit output current	$V_O = V_{CC}$ or GND ⁽³⁾		–30	–150	mA
I_{CC}	Supply current (total package)	$V_I = V_{CC}$ or GND, No load, enable			100	μA
C_{pd}	Power dissipation capacitance	No load ⁽⁴⁾		160		pF

(1) All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

(2) Refer to TIA-EIA-422-B for exact conditions.

(3) Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

(4) C_{pd} determines the no-load dynamic current consumption. $I_S = C_{pd} \times V_{CC} \times f + I_{CC}$

SWITCHING CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
t_{PHL}	Propagation delay time, high- to low-level output	See Figure 2	4	8	12	ns
t_{PLH}	Propagation delay time, low- to high-level output		4	8	12	ns
t_t	Transition time (t_r or t_f)	See Figure 2		5	10	ns
t_{PZH}	Output-enable time to high level	See Figure 3		10	20	ns
t_{PZL}	Output-enable time to low level	See Figure 4		10	20	ns
t_{PHZ}	Output-disable time from high level	See Figure 3		10	20	ns
t_{PLZ}	Output-disable time from low level	See Figure 4		10	20	ns
$t_{sk(p)}$	Pulse skew	See Figure 2 ⁽²⁾⁽³⁾		0.5	1.5	ns
$t_{sk(o)}$	Skew limit (pin to pin)				1.5	ns
$t_{sk(lim)}$	Skew limit (device to device)				3	ns
$f_{(max)}$	Maximum operating frequency	See Figure 2		32		MHz

(1) All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

(2) Pulse skew is defined as the $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

(3) Skew limit (device to device) is the maximum difference in propagation delay times between any two channels of any two devices.

ESD PROTECTION

PARAMETER	TEST CONDITIONS	TYP	UNIT
Driver output	HBM	±15	kV
	IEC61000-4-2, Air-Gap Discharge	±15	
	IEC61000-4-2, Contact Discharge	±8	

PARAMETER MEASUREMENT INFORMATION

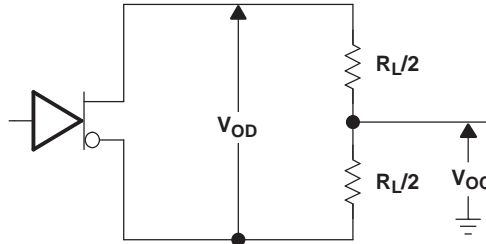
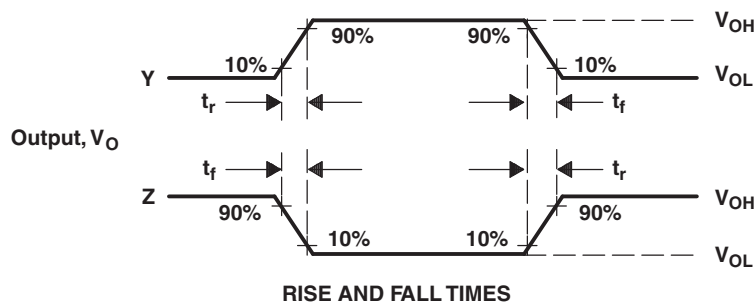
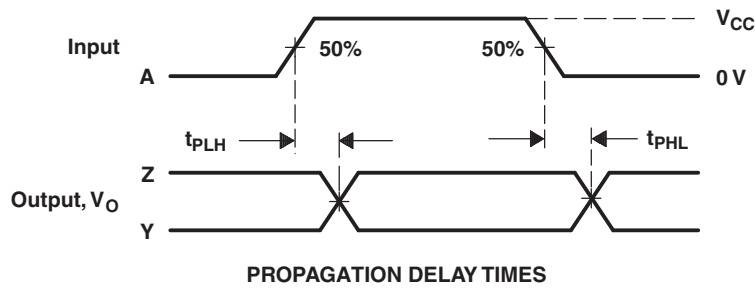
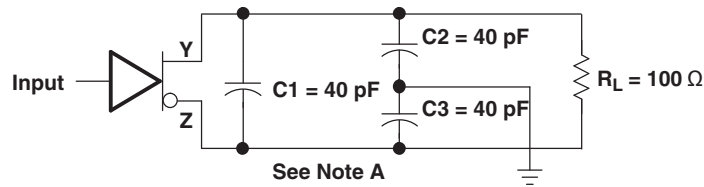


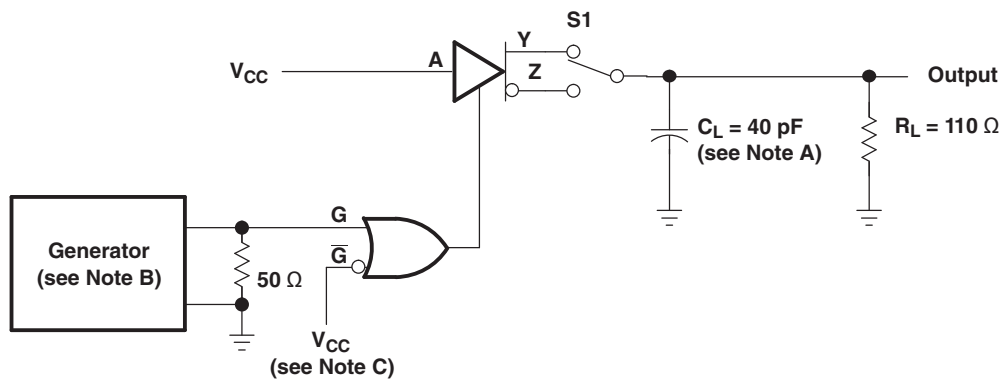
Figure 1. Test Circuit, V_{OD} and V_{OC}



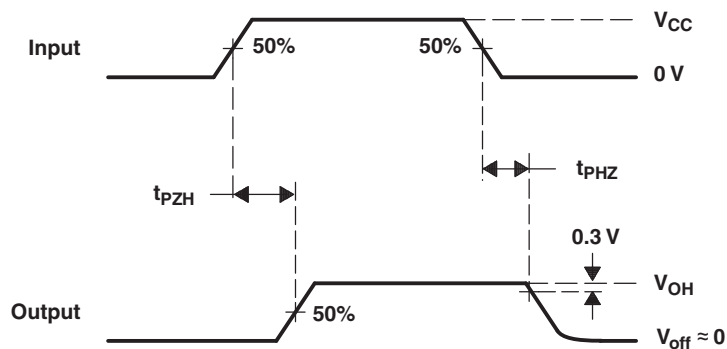
- NOTES: A. C_L includes probe and jig capacitance.
 B. The input pulse is supplied by a generator having the following characteristics: PRR = 32 MHz, 50% duty cycle, t_r and $t_f \leq 2$ ns.

Figure 2. Test Circuit and Voltage Waveforms, t_{PHL} and t_{PLH}

PARAMETER MEASUREMENT INFORMATION (continued)



TEST CIRCUIT

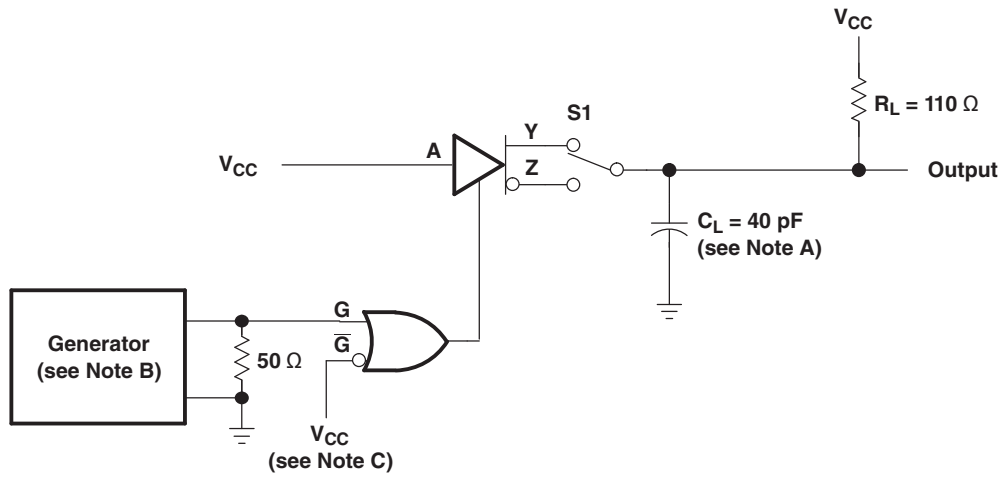


VOLTAGE WAVEFORMS

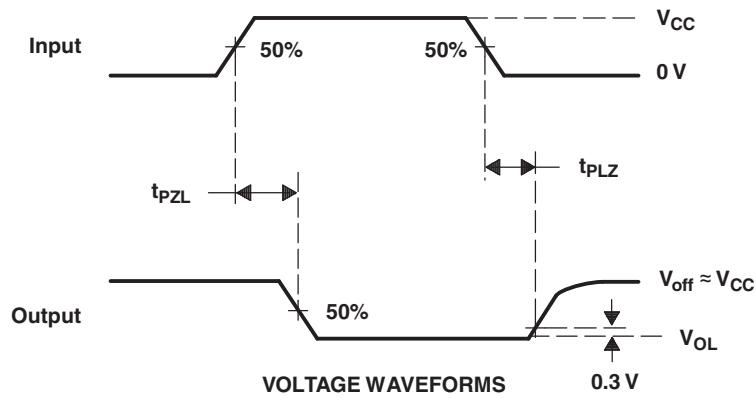
- NOTES: A. C_L includes probe and jig capacitance.
 B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, 50% duty cycle, t_r and $t_f \leq 2$ ns.
 C. To test the active-low enable \bar{G} ground G and apply an inverted waveform to \bar{G}

Figure 3. Test Circuit and Voltage Waveforms, t_{PZH} and t_{PHZ}

PARAMETER MEASUREMENT INFORMATION (continued)



TEST CIRCUIT



VOLTAGE WAVEFORMS

- NOTES: A. C_L includes probe and jig capacitance.
 B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, 50% duty cycle, t_r and $t_f \leq 2$ ns.
 C. To test the active-low enable \overline{G} ground G and apply an inverted waveform to \overline{G}

Figure 4. Test Circuit and Voltage Waveforms, t_{PZL} and t_{PLZ}

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
AM26LV31EIDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM26LV31EI	Samples
AM26LV31EIDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM26LV31EI	Samples
AM26LV31EINSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	26LV31EI	Samples
AM26LV31EIPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	SB31	Samples
AM26LV31EIPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	SB31	Samples
AM26LV31EIRGYR	ACTIVE	VQFN	RGY	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	SB31	Samples
AM26LV31EIRGYRG4	ACTIVE	VQFN	RGY	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	SB31	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF AM26LV31E :

- Enhanced Product: [AM26LV31E-EP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AM26LV31EIDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26LV31EIPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
AM26LV31EIRGYR	VQFN	RGY	16	3000	330.0	12.4	3.8	4.3	1.5	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
AM26LV31EIDR	SOIC	D	16	2500	367.0	367.0	38.0
AM26LV31EIPWR	TSSOP	PW	16	2000	367.0	367.0	35.0
AM26LV31EIRGYR	VQFN	RGY	16	3000	367.0	367.0	35.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211284-3/G 08/15

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4203539-3/1 06/2011

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - Package complies to JEDEC MO-241 variation BA.

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

4206353-3/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-3/P 03/14

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Texas Instruments:](#)

[AM26LV31EINSRG4](#)